



# Eternal Semiconductor Inc.

## EV2315

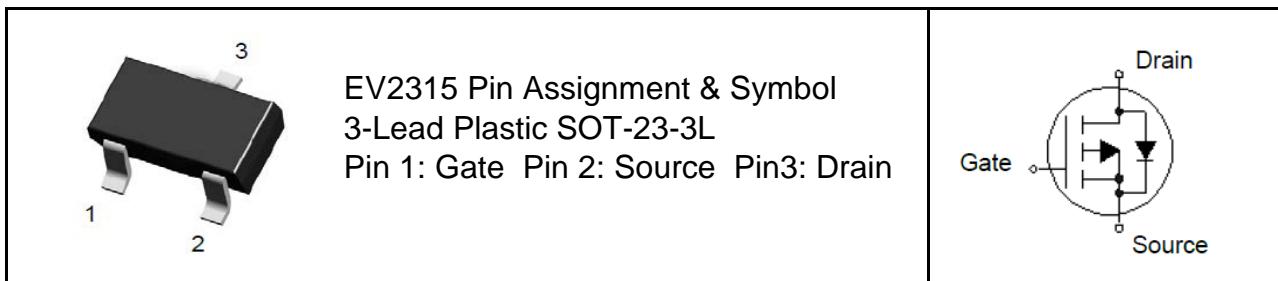
### P-Channel Enhancement-Mode MOSFET (-20V, -5.9A)

#### PRODUCT SUMMARY

$V_{DSS}$	$I_D$	$R_{DS(on)}$ (mΩ)Max
-20V	-5.9A	22 @ $V_{GS} = -4.5$ V, $I_D = -5.9$ A
		29 @ $V_{GS} = -2.5$ V, $I_D = -3.0$ A
		45 @ $V_{GS} = -1.8$ V, $I_D = -1.5$ A

#### Features

- Super high dense cell trench design for low RDS(on)
- Rugged and reliable
- SOT-23-3L package
- Lead (Pb) -free and halogen-free



#### Absolute Maximum Ratings ( $T_A=25^\circ\text{C}$ , unless otherwise noted)

Symbol	Parameter	Ratings	Units
$V_{DS}$	Drain-Source Voltage	-20	V
$V_{GS}$	Gate-Source Voltage	$\pm 12$	V
$I_D$	Drain Current (Continuous)	-5.9	A
$I_{DM}$	Drain Current (Pulsed) <sup>a</sup>	-24	A
$P_D$	Total Power Dissipation @ $T_A=25^\circ\text{C}$	1.7	W
$I_S$	Maximum Diode Forward Current	-1	A
$T_j, T_{stg}$	Operating Junction and Storage Temperature Range	-55 to +150	°C
$R_{QJA}$	Thermal Resistance Junction to Ambient (PCB mounted) <sup>b</sup>	75	°C/W

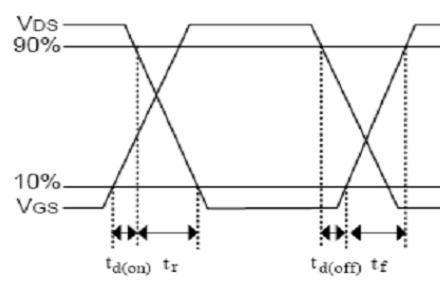
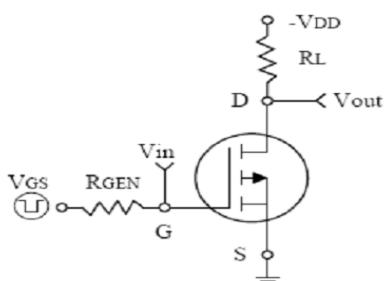
a: Repetitive Rating: Pulse width limited by the maximum junction temperature.

b: 1-in<sup>2</sup> 2oz Cu PCB board

### Electrical Characteristics ( $T_A=25^\circ C$ , unless otherwise noted)

Symbol	Characteristic	Test Conditions	Min.	Typ.	Max.	Unit
<b>• Off Characteristics</b>						
$BV_{DSS}$	Drain-Source Breakdown Voltage	$V_{GS}=0V, I_D=-250\mu A$	-20	-	-	V
$I_{DSS}$	Zero Gate Voltage Drain Current	$V_{DS}=-20V, V_{GS}=0V$	-	-	1	$\mu A$
$I_{GSS}$	Gate-Body Leakage Current	$V_{GS}=\pm 12V, V_{DS}=0V$	-	-	$\pm 100$	nA
<b>• On Characteristics</b>						
$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS}=V_{GS}, I_D=-250\mu A$	-0.45		-1	V
$R_{DS(on)}$	Drain-Source On-State Resistance	$V_{GS}=-4.5V, I_D=-5.9A$	-	22	28	$m\Omega$
		$V_{GS}=-2.5V, I_D=-3A$		29	38	
		$V_{GS}=-1.8V, I_D=1.5A$	-	45	56	
<b>• Dynamic Characteristics</b>						
$C_{iss}$	Input Capacitance	$V_{DS}=-10V, V_{GS}=0V, f=1MHz$	-	2100	-	PF
$C_{oss}$	Output Capacitance		-	497	-	
$C_{rss}$	Reverse Transfer Capacitance		-	289	-	
<b>• Switching Characteristics</b>						
$Q_g$	Total Gate Charge	$V_{DS}=-10V, I_D=-1A, V_{GS}=-10V$	-	18	-	nC
$Q_{gs}$	Gate-Source Charge		-	4.2	-	
$Q_{gd}$	Gate-Drain Charge		-	4.5	-	
$t_{d(on)}$	Turn-on Delay Time	$V_{DD}=-10V, R_L=15\Omega, I_D=1A, VGEN=-4.5V, RG=10\Omega$	-	25	-	nS
$t_r$	Turn-on Rise Time		-	33	-	
$t_{d(off)}$	Turn-off Delay Time		-	56	-	
$t_f$	Turn-off Fall Time		-	46	-	
<b>• Drain-Source Diode Characteristics</b>						
$V_{SD}$	Drain-Source Diode Forward	$V_{GS}=0V, I_S=-1A$	-	-	-1.2	V

Note: Pulse Test: Pulse Width  $\leq 300\mu s$ , Duty Cycle  $\leq 2\%$



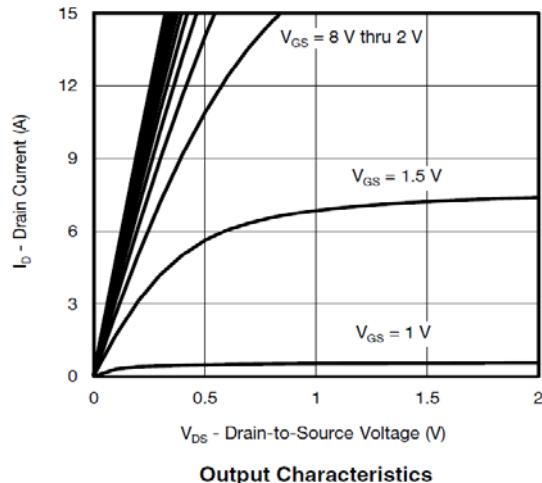
Switching Test Circuit and Swithching Waveforms



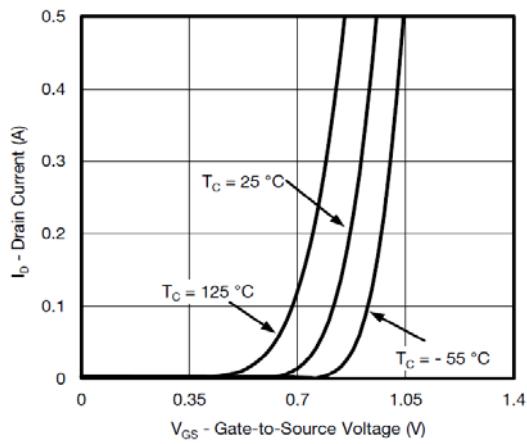
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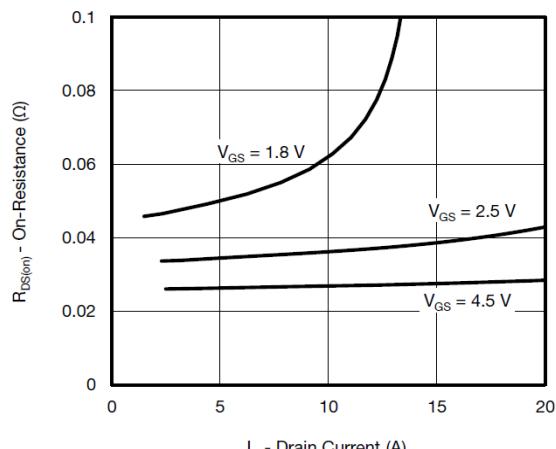
### Typical Characteristics Curves (Ta=25°C, unless otherwise note)



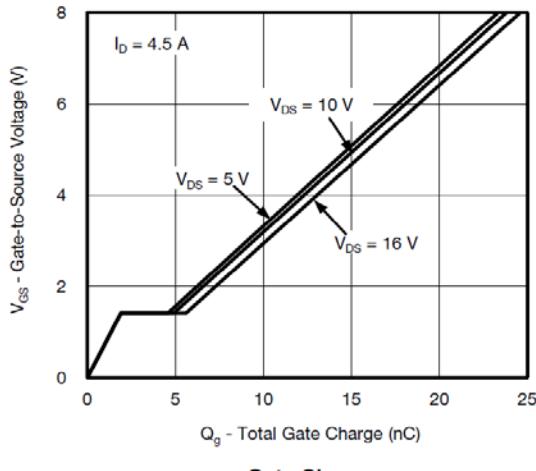
Output Characteristics



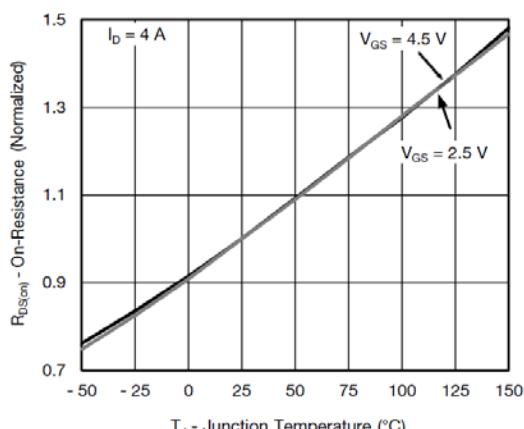
Transfer Characteristics



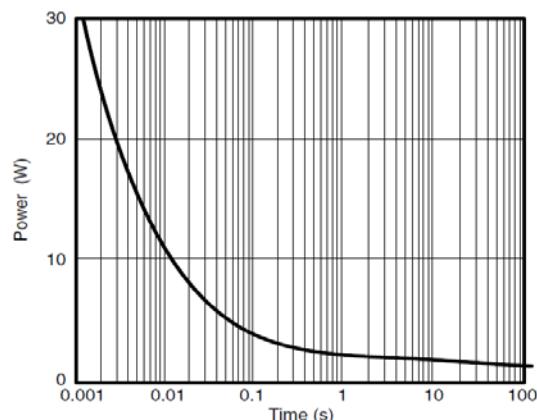
On-Resistance vs. Drain Current



Gate Charge



On-Resistance vs. Junction Temperature

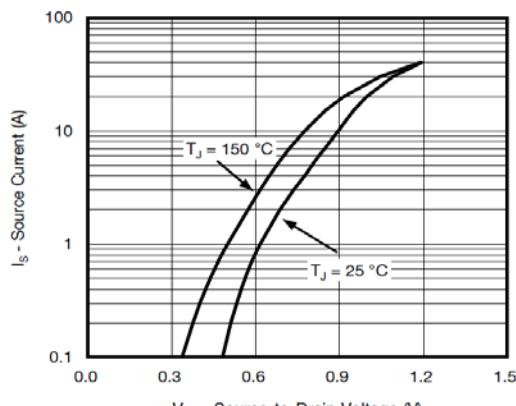


Single Pulse Power, Junction-to-Ambient

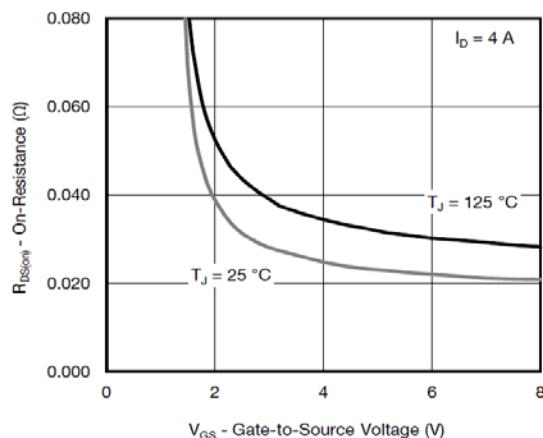


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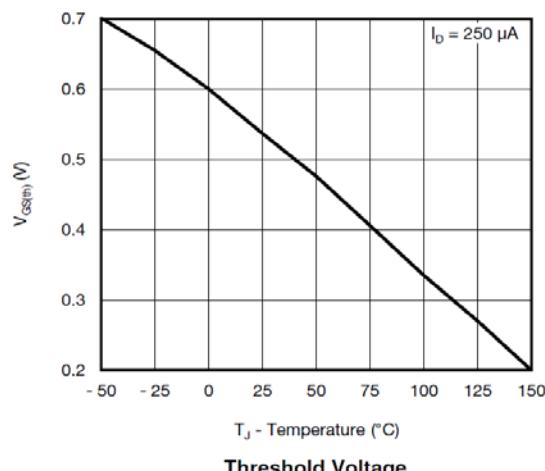
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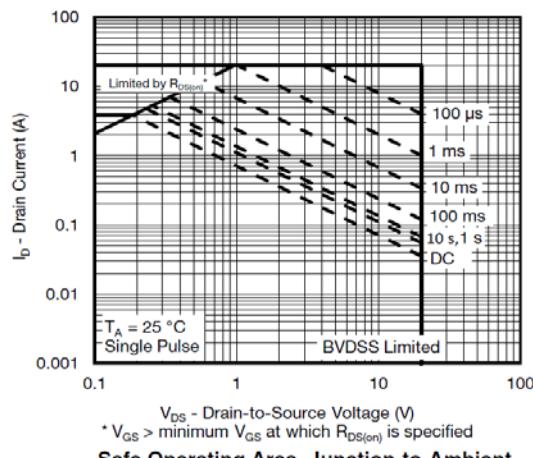
Source-Drain Diode Forward Voltage



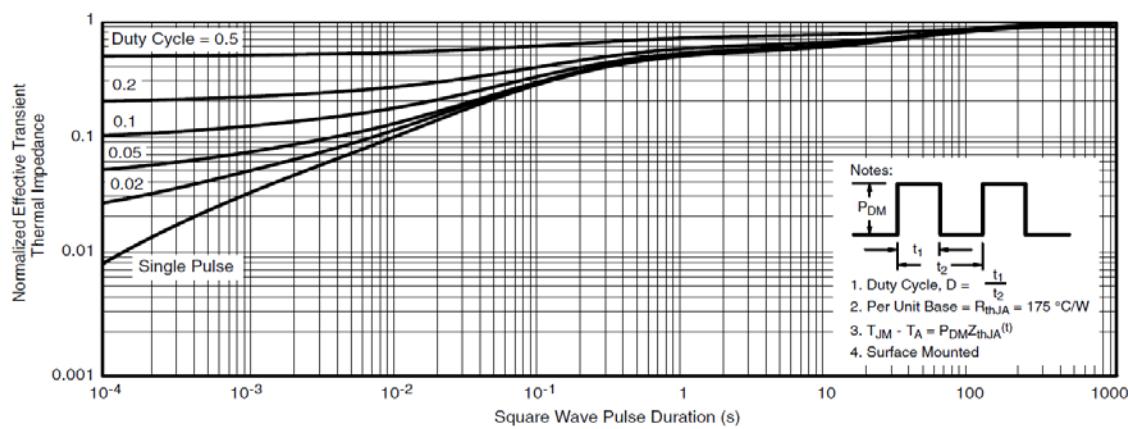
On-Resistance vs. Gate-to-Source Voltage



Threshold Voltage



Safe Operating Area, Junction-to-Ambient



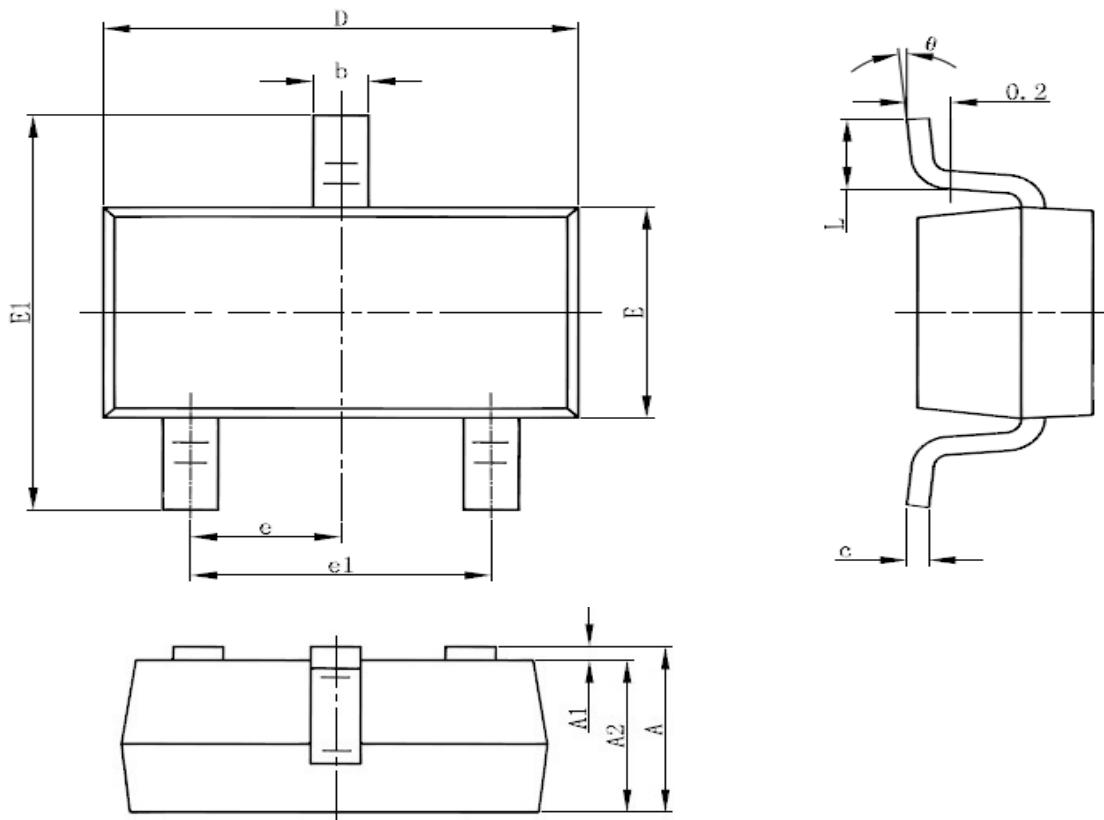
Normalized Thermal Transient Impedance, Junction-to-Ambient



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### SOT23-3L PACKAGE OUTLINE DIMENSIONS



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A	0.850	1.250	0.033	0.049
A1	0.000	0.100	0.000	0.004
A2	0.7	1.150	0.028	0.045
b	0.300	0.500	0.012	0.020
c	0.100	0.200	0.004	0.008
D	2.820	3.020	0.111	0.119
E	1.500	1.700	0.059	0.067
E1	2.650	2.950	0.104	0.116
e	0.950(BSC)		0.037(BSC)	
e1	1.800	2.000	0.071	0.079
L	0.300	0.600	0.012	0.024
θ	0°	8°	0°	8°